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technical sheet

/ ORACL

Tool to perform controlled longitudinal scoring on peelable semiconductor



/ Use

The ORACL enables the user to score longitudinally the peelable semiconductive layer in order to peel it off by hand.

Adjustable scoring depths (0.4 / 0.6 / 0.9 / 1.1 mm)

/ Advantages

- Robust design
- Ajustement rapide de 4 profondeurs de coupe
- 4 cutting depths
- Des stries au dos de l'outil qui facilitent la préhension du semiconducteur après incision

/ Areas of activity

-  Cable & Connections
-  Electrical distribution
-  Industry

/ Technical specifications

- **Specific tools :** Cable tools
- **Cable tools :** Cable tools
- **Areas of activity :** Cable & Connections, Electrical distribution, Industry
- **For network cables :** medium voltage
- **Packaging :** Carton box
- **Weight (g) :** 160
- **Lenght (mm) :** 135
- **Width (mm) :** 55

- **Height (mm) :** 35
- **Max diameter (mm) :** 100
- **Mini diameter (mm) :** 10
- **Remining length of semi conductor (MIN) (mm) :** 10 (gaine) / 4 (écran)
- **Scoring depth MAX (mm) :** 1.1
- **Longitudinal cutting depth (mm) :** 0.4 / 0.6 / 0.9 / 1.1
- **Tools king :** Specific tools

/ Spare parts

	Reference	Designation
	LSO	Blade for cutting the peelable semiconductor of MV cables

/ Associated products

	Reference	Designation
	DSP	Peelable semiconductor lifter
	MVS	Stop for tools